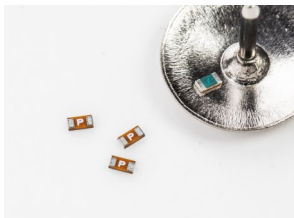


## TF-FUSE<sup>®</sup> Thin Film Surface Mount Fuses

### T0603HI Series (High Inrush, 0603 Size)



#### Features:

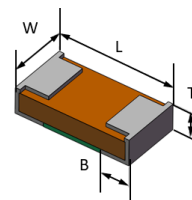
- Low DCR and low profile
- High inrush current withstanding capability
- Fiberglass enforced epoxy fuse body
- Copper termination with nickel and tin plating

#### Clearing Time Characteristics:

% of current rating	Clearing time at 25°C	
	Min.	Max.
100%	4 hours	-
200%	1 second	60 seconds
1000%	0.0002 seconds	0.02 seconds

#### Shape and Dimensions:

Unit	Inch	mm
L	0.063 ± 0.004	1.60 ± 0.10
W	0.032 ± 0.004	0.81 ± 0.10
T	0.014 ± 0.004	0.36 ± 0.10
B	0.014 ± 0.004	0.36 ± 0.10



#### Applications:

- Power tools
- DC-DC convert
- Panel & PC
- Server
- Battery pack
- Set top box

#### Ordering Information:

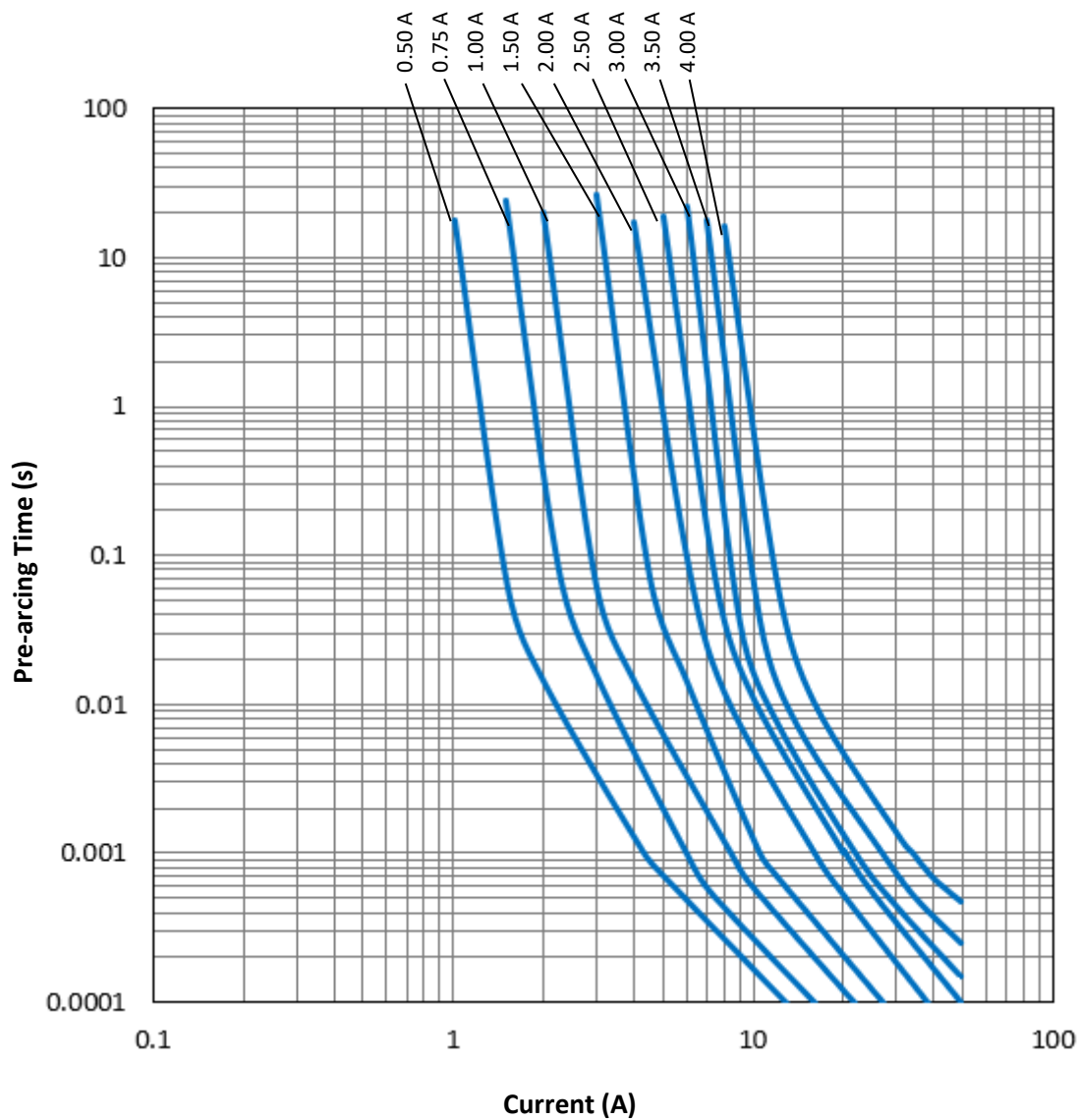
Part Number	Current Rating (A)	Voltage Rating (V DC)	Interrupting Rating	Nominal Cold DCR ( $\Omega$ ) <sup>1</sup>	Nominal $I^2t$ ( $A^2s$ ) <sup>2</sup>	Marking <sup>3</sup>
T0603HI0500TM	0.50	65	50A@35V DC/AC 13A@65V DC	0.1550	0.019	C
T0603HI0750TM	0.75	65		0.0830	0.036	D
T0603HI1000TM	1.00	65		0.0500	0.052	E
T0603HI1500TM	1.50	65		0.0290	0.110	T
T0603HI2000TM	2.00	35	35A@35V DC/AC 50A@24V DC/AC	0.0200	0.310	F
T0603HI2500TM	2.50	35		0.0165	0.400	J
T0603HI3000TM	3.00	35		0.0140	0.600	L
T0603HI3500TM	3.50	35		0.0120	0.800	N
T0603HI4000TM	4.00	35		0.0095	1.200	P

1. Measured at  $\leq 10\%$  rated current and 25 °C ambient.
2. Melting  $I^2t$  at 0.001 sec.
3. White marking character code.

## TF-FUSE<sup>®</sup> Thin Film Surface Mount Fuses

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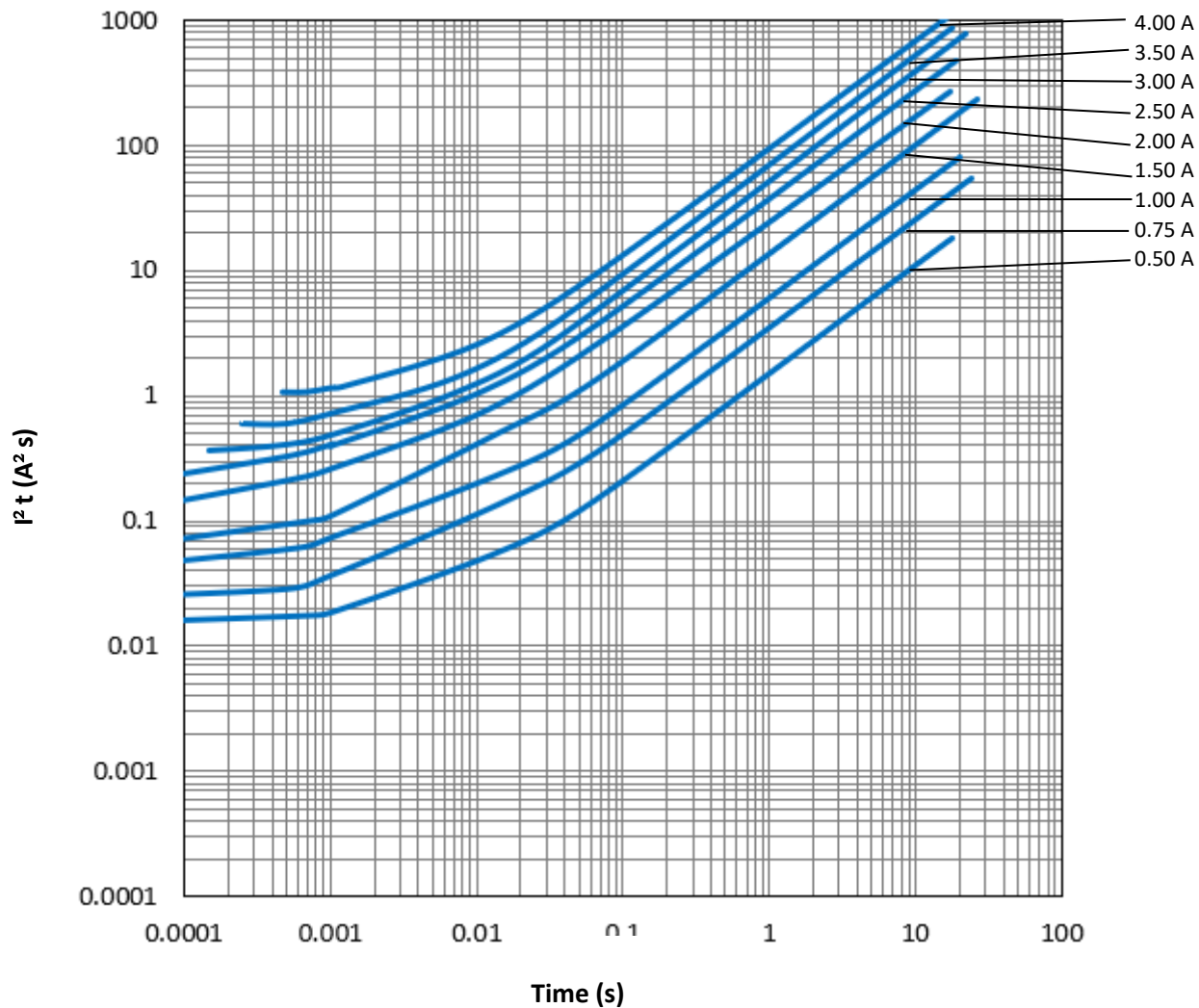
### Average Pre-arcing Time Curves:



## TF-FUSE® Thin Film Surface Mount Fuses

T0603HI Series (High Inrush, 0603 Size)

### Average $I^2t$ vs. t Curves:

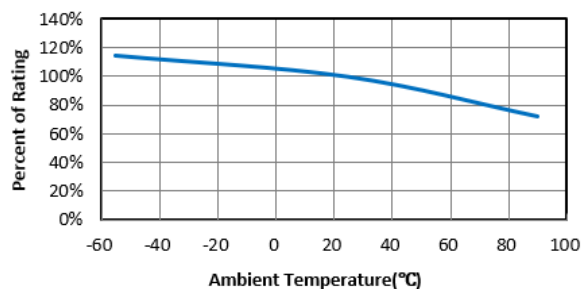


## TF-FUSE<sup>®</sup> Thin Film Surface Mount Fuses

### T0603HI Series (High Inrush, 0603 Size)

#### Temperature De-rating:

The ambient temperature affects the current carrying capacity of fuses. When a fuse is operating at a temperature higher than 25°C, the fuse shall be “de-rated” according to the de-rating curve.



#### Operating Temperature Range:

- 55°C ~+90°C (with de-rating)

#### Product Identification:

**T 0603 HI 0500 T M**

(1) (2) (3) (4) (5)(6)

(1) **Series Code:** Thin Film Surface Mount Fuses

(2) **Size Code:** L x W (inch), the first two digits - L (length), the last two digits - W (width)

(3) **Characteristic Code:** HI - High Inrush

(4) **Current Rating Code:** 0500 - 0.50A

(5) **Package Code:** T - Tape & Reel, B - Bulk

(6) **Marking Code:** M—With marking

#### Agency Approval:

- Recognized Under the Components Program of Underwriters Laboratories.
- Certification #: UL-E232989

#### Reliability Tests:

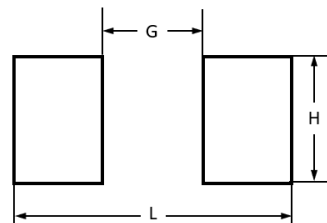
No.	Item	Condition	Criteria
1	Bend	2 mm bend	DCR change within $\pm 20\%$ ( $\pm 10\%$ for $\leq 1A$ ), no mechanical damage
2	Solderability	245°C, 5 seconds	New solder coverage $\geq 95\%$
3	Life	75% rated current, 2000 hours, ambient temperature +20°C to +30°C	No open circuit, voltage drop change within $\pm 10\%$
4	Thermal Shock	-55°C to +125°C, 100 cycles	DCR change within $\pm 10\%$ , no mechanical damage
5	Mechanical Vibration	5 – 3000 Hz, 0.4 inch double amplitude or 30 G peak	DCR change within $\pm 10\%$ , no mechanical damage
6	Mechanical Shock	1500 G, 0.5 milliseconds, half-sine shocks	DCR change within $\pm 10\%$ , no mechanical damage
7	Salt Spray	5% salt solution, 48 hours exposure	DCR change within $\pm 10\%$ , no excessive corrosion
8	Moisture Resistance	10 cycles	DCR change within $\pm 10\%$ , no excessive corrosion

## TF-FUSE<sup>®</sup> Thin Film Surface Mount Fuses

### T0603HI Series (High Inrush, 0603 Size)

#### Recommended Land Pattern:

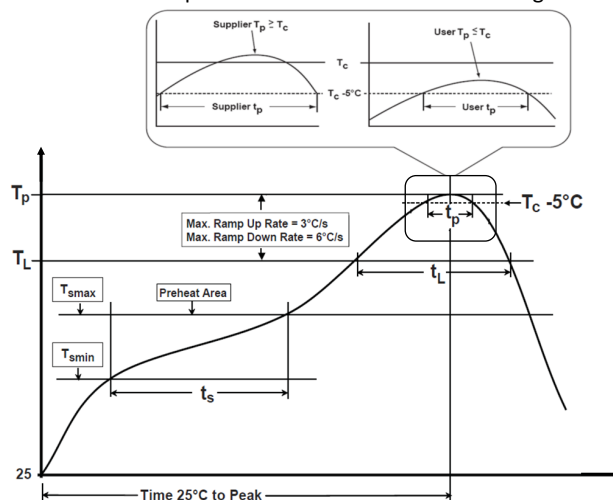
Chip Size	0603	Unit
L	0.087 (2.2)	Inch (mm)
G	0.031 (0.8)	Inch (mm)
H	0.039 (1.0)	Inch (mm)



#### Recommended Temperature Profile:

Profile Feature	Pb-Free Assembly
<b>Preheat/Soak</b>	
Temperature Min ( $T_{smin}$ )	150°C
Temperature Max ( $T_{smax}$ )	200°C
Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	60~120 seconds
Ramp-up rate ( $T_L$ to $T_p$ )	3°C/second max.
Liquidous temperature ( $T_L$ )	217°C
Time ( $t_L$ ) maintained above $T_L$	60~150 seconds
Peak package body temperature ( $T_p$ )	260°C
Time ( $t_p$ )*within 5°C of the specified classification temperature ( $T_c$ )	30 seconds *
Ramp-down rate ( $T_p$ to $T_L$ )	6°C/second max.
Time 25°C to peak temperature	8 minutes max.
* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum	

#### \* Recommended Temperature Profile for Reflow Soldering



#### Recommended conditions for hand soldering:

- Appropriate temperature (max.) of soldering iron tip/soldering time (max.): 280°C / 10 s or 350°C / 3 s
- Using hot air rework station with tip that can melt the solder on both terminations at the same time is strongly recommended. Do not directly contact the chip termination with the tip of soldering iron.

#### Storage:

- The maximum ambient temperature shall not exceed 35°C . Storage temperatures higher than 35°C could result in the deformation of packaging materials.
- The maximum relative humidity recommended for storage is 75%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components.
- The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.
- MSL=1

#### Packaging:

Chip Size	Parts on 13 inch (330 mm) Reel
0603	8,000

## Disclaimer

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